

The product using material and processing must conform to the "WL-PZ-001" HSF technical standard control requirements

RoHS+HF

NOTES:

1.MATERIAL: SEE SHEET

2. FINISH:

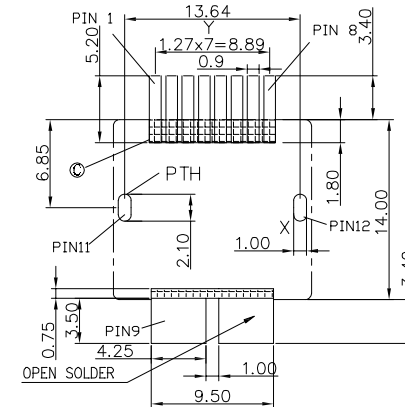
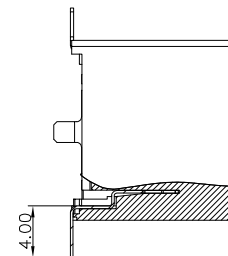
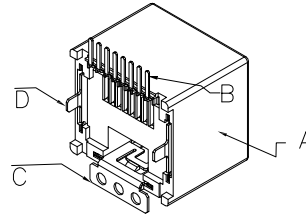
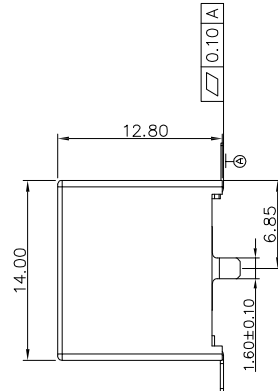
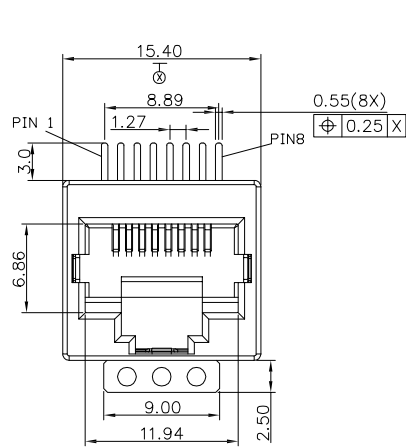
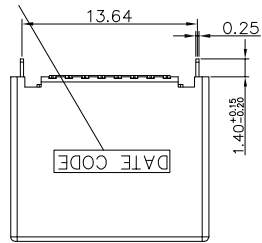
2.1 TERMINAL: NICKEL UNDERPLATING OVER ALL.GOLD FLASH ON CONTACT AREA, MATTE TIN 100u" ON SOLDER AREA.

2.2 SHELL: UNDERPLATED: NICKEL PLATING OVER ALL.

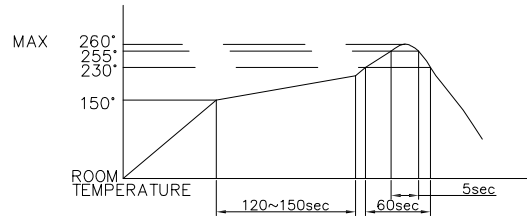
3. HALOGEN FREE & RoHS COMPLIANT PRODUCTS.

4. FOR IR SOLDERING LEAD-FREE PROCESS.260°C, 5~10SECS.

OR PRINTED ON THE OPPOSITE



RECOMMENDED P.C.BOARD LAYOUT  
(TOP SIDE) TOLERANCE=±0.05mm  
PATTERN PROHIBITED AREA



REFLOW PROFILE :FOR IR SOLDERING LEAD-FREE PROCESS.255~260°C, 5~10SECS.

P/N	Terminal Plating
WLR4F0-0821A0109	G/F

ITEM	DESCRIPTION	REMARK	Q'TY
Ⓒ	DIP	METAL ALLOY , TIN PLATING	2
Ⓒ	FOOT	METAL ALLOY , TIN PLATING	1
Ⓑ	CONTACT	COPPER ALLOY , GOLD PLATING ON CONTACT AREA	1SET
Ⓐ	HOUSING	HIGH TEMP THERMOPLASTIC ,UL94V-0, BLACK	1

REV.	REVISION RECORD	DATE	GENERAL TOLERANCES		SCALE:	NAME	DATE	PART.NO:	DWG.NO:	 WanLian Teconology Co., Ltd REV: A0 SHEET: 1/1
AO	NEW RELEASE	22.05.09	LINEAR	ANGLES	1:1	Wang_jr	22.05.09	WLR4F0-0821A0109	ENDE05	
			0.0±0.35	X'REF±6'	APPROVED	Han_Gao	22.05.09	TITLE:		
			UNIT:mm	X'±3'	DESIGNER	LanXuan_Hou	22.05.09	CONN,RJ45 RECEPTACLE SMT, VERTICAL,W/O LED		
			SIZE: A4	0.000±0.10	X'X' ±2'	DRAWN				